

DSW

PATENT

Appl. No. 10/712,708
Amdt. dated Dec. 22, 2006
Reply to Office action of Oct. 6, 2006



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re the application of:)	
)	Group Art Unit: 3744
CHEN et al.)	
)	Examiner: Ciric, L.
Application No: 10/712,708)	
)	Docket No: JLINP174/TLC
Filed: November 12, 2003)	
)	Date: December 22, 2006
For: HEAT DISSIPATION MODULE)	
_____)	

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited
with the United States Postal Service as First Class Mail in an
envelope addressed to: Commissioner for Patents, Alexandria,
VA 22313-1450 on December 22, 2006.

Signed: _____
Al Penilla

Honorable Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

In response to the Office Action dated October 6, 2006, the term to respond
extends to January 8, 2007. Please enter this amendment and remarks.

Amendments to the Specification begin on page 2 of this paper.

Amendments to the claims are reflected in the listing of claims which begin on
page 6 of this paper.

Remarks/Arguments begin on page 10 of this paper.